PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 EPAS ID: PAT3845111 Stylesheet Version v1.2

SUBMISSION TYPE: NEW ASSIGNMENT

NATURE OF CONVEYANCE: ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
DON LEE	01/28/2016
DANIEL LAM	01/28/2016
ROGER MCALEENAN	01/28/2016
KOSUKE MIYAO	01/28/2016

RECEIVING PARTY DATA

Name:	ADVANTEST CORPORATION	
Street Address:	1-32-1 ASAHI-CHO, NERIMA-KU	
City:	TOKYO	
State/Country:	JAPAN	
Postal Code:	179-0071	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	15016143

CORRESPONDENCE DATA

Fax Number: (408)938-9069

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: (408)938-9060

Email: officeaction@mhbpatents.com
Correspondent Name: MURABITO, HAO & BARNES LLP
Address Line 1: 2 NORTH MARKET STREET

Address Line 2: THIRD FLOOR

Address Line 4: SAN JOSE, CALIFORNIA 95113

ATTORNEY DOCKET NUMBER:	ATSY-0030-01.01US
NAME OF SUBMITTER:	ANTHONY C. MURABITO
SIGNATURE:	/Anthony C. Murabito/
DATE SIGNED:	04/25/2016

Total Attachments: 1

source=ATSY-0030-0101US_ASSIGNEMENT#page1.tif

PATENT REEL: 038373 FRAME: 0252

503798464

Attorney Docket No.: ATSY-0030-01.01US

Assignment to Advantest Corporation

In consideration of good and valuable consideration, receipt of which is hereby acknowledged. I/we DON LEE, DANIEL LAM, ROGER MCALEENAN, KOSUKE MIYAO do hereby sell, assign, and transfer unto Advantest Corporation (hereinafter called Advantest), a Japanese Corporation having its principal place of business at 1-32-1 Asahi-Cho, Nerima-Ku Tokyo, Japan 179-0071, and its successors and assigns, the entire right, title, and interest for the United States and all foreign countries, in and to any and all improvements, including the right of priority in, to, and under, the application for the United States patent entitled: PLATING METHODS FOR MODULAR AND/OR GANGED WAVEGUIDES FOR AUTOMATIC TEST EQUIPMENT FOR SEMICONDUCTOR TESTING X filed herewith and the inventions set forth and described therein, and any and all Letters Patent of the United States and of countries foreign thereto which may be granted thereon or therefor; or and the inventions set forth filed on and described therein, and any and all Letters Patent of the United States and of countries foreign thereto which may be granted thereon or therefor; And for the above consideration, I/we agree promptly upon request of Advantest, its successors or assigns, to execute and deliver without further compensation any power of attorney, assignment, application, whether original, continuation, divisional or reissue, or other papers which may be necessary or desirable fully to secure to Advantest, its successors and assigns, the inventions described in said application and all patent rights therein, in the United States and in any country foreign thereto, and to cooperate and assist in the prosecution of interference proceedings involving said inventions and in the adjudication or reexamination of said Letters Patent provided the expenses which may be incurred by me/us in lending such cooperation and assistance are paid by Advantest. I/we further covenant with Advantest, its successors, assigns, and legal representatives that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned; In witness whereof, I/we hereunto set my/our hand(s) and seal: Inventor's Signature: DON LEE Inventor's Signature: DANIEL LAM Inventor's Signature: ROGER MCALEENAN

Page 1 of 1

RECORDED: 04/25/2016

Inventor's Signature: KOSUKE MIYAO

rev. 11/97 epn